

Impact-S Scalable 2000

Specifications

The information is believed to be accurate. However Amplicon Liveline Limited accepts no responsibility for any problems caused by errors and omissions. Specifications are subject to change without notice.

Hardware Specification	CPU ¹ : Single/Dual Intel® Xeon® Scalable "Socket P" Chipset: Intel® C624 Main memory ² : Base RAM 32GB ECC DDR4 2666MHz QPI Links: 2 RAID Support: 0,1,10,5,50,6,60 Integrated features ³ : IPMI, BMC, SMM Video: VGA (DB15) LAN: Dual 10GbE TPM: 2.0	Advanced Technology Support	Intel® Optane™ Memory Supported _____ Yes Intel® Virtualization Technology for Directed I/O (VT-d) _____ Yes Intel® Remote Management Module Support _____ Yes Intel® Node Manager _____ Yes Intel® Quick Resume Technology _____ No Intel® Quiet System Technology _____ No Intel® HD Audio Technology _____ No Intel® Rapid Storage Technology enterprise _____ Yes Intel® Fast Memory Access _____ Yes Intel® Flex Memory Access _____ Yes Intel® I/O Acceleration Technology _____ Yes Intel® Advanced Management Technology _____ Yes Intel® Server Customization Technology _____ Yes Intel® Build Assurance Technology _____ Yes Intel® Efficient Power Technology _____ Yes Intel® Quiet Thermal Technology _____ Yes
Disk Capacity	Impact-S S2012: Front: 12 x 3.5" HDD ⁴ Rear: 2 x 2.5" xDD ⁵ Impact-S S2024: Front: 24 x 2.5" xDD ⁵ (support for up to 2 NVMe drives) Rear: 2 x 2.5" xDD ⁵ Internal [BOTH]: 2 x M.2 (Function Spec TBC)	Environmental Operation	Acoustic noise: Approximately 50dBA sound pressure at 23°C (typical) Temperature: 0 to 45°C Humidity: 5 to 90% at 25°C non-condensing
System Expansion ⁶	Default Option (PCIe Rev. 3.0): 7 PCIe x8 slots 1 PCIe x4	Environmental Storage	Temperature: -20 to 65°C Humidity: 5 to 90% at 25°C non-condensing
Supported Operating System(s)	Server 2016 Linux (call to confirm)	Electromagnetic Compatibility (EMC)	LV Directive 2014/35/EU EN 60950-1:2006 + A11:2009 + A12:2011 + A1:2010 + A2:2013 EMC Directive 2014/30/EU EN 55032: 2012 +AC: 2013 (Non-Harmonized) EN 55024: 2010 (Non-Harmonized) EN 61000-3-2: 2014 EN 21000-3-3: 2013 Additional declarations FCC, 47 CFR Part 15, Class A digital device (USA) IEC 61000-4-2: 2008 IEC 61000-4-3: 2006 with amendment 1:2007 and Amendment 2:2010 IEC 61000-4-4: 2012 IEC 61000-4-5: 2014 IEC 61000-4-6: 2013 IEC 61000-4-8: 2009 IEC 61000-4-11: 2004
Interface/Switches	Front: Dual USB 3.0 Power s/w ID LED		
Mechanical (W x D x H)	Dimensions: 430mm x 709.93mm x 87.38mm (16.93" x 27.95" x 3.44")		

¹ Bronze, Silver, Gold and Platinum grade ≤140W TDP

² Upgradable to 3TB over 24 DIMMs

³ Intelligent Platform Management Interface (IPMI), Baseboard Management Controller (BMC), System Management Mode (SMM)

⁴ Caddies will except 2.5" xDD

⁵ Up to 15mm tall drives

⁶ Optional Configuration available (2 PCIe x16, 3 PCIe x8, 1 PCIe x4)